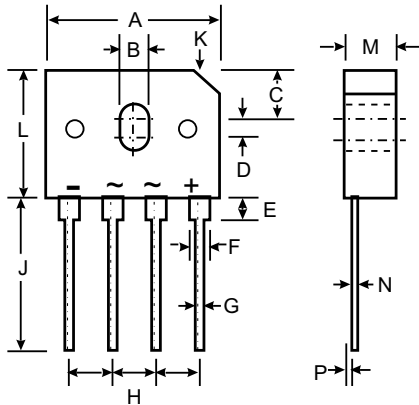




GBU		
Dim	Min	Max
A	21.8	22.3
B	3.5	4.1
C	7.4	7.9
D	1.65	2.16
E	2.25	2.75
G	1.02	1.27
H	4.83	5.33
J	17.5	18.0
K	3.2 X 45°	
L	18.3	18.8
M	3.30	3.56
N	0.46	0.56
P	0.76	1.0
All Dimensions in mm		

Features

- Glass passivated die construction
- Low forward voltage drop
- High current capability
- High surge current capability
- Plastic material-UL flammability 94V-0

Mechanical Data

- Case: GBU, molded plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Case
- Mounting Position: Any
- Marking: Type Number
- Lead Free: For RoHS / Lead Free Version

Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified.

Single Phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

TYPE NUMBER	SYMBOL	GBU 15005	GBU 1501	GBU 1502	GBU 1504	GBU 1506	GBU 1508	GBU 1510	UNITS
Peak Repetitive Reverse Voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Working Peak Reverse Voltage	V _{RWM}								
DC Blocking Voltage	V _{DC}								
RMS Reverse Voltage	V _{RMS}	35	70	140	280	420	560	700	V
Average Rectified Output Current (Note 1)@T _C =90℃	I _{F(AV)}	15.0							A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	200							A
Forward Voltage per element @I _F =7.5A @I _F =15A	V _{FM}	1.0 1.1							V
Peak Reverse Current @T _A =25℃ At Rated DC Blocking Voltage @T _A =125℃	I _R	5.0 500							uA
I ² t Rating for fusing (t <8.3ms)	I ² t	166							A ² s
Typical Junction Capacitance per leg (Note 2)	C _J	70							pF
Typical Thermal Resistance per leg (Note 3)	R _{θJA}	30.9							℃/W
	R _{θJL}	7.3							
Operating and Storage Temperature Range	T _J ,T _{STG}	-55to+150							℃

Note: 1. Mounted on glass epoxy PC board with 1.3mm² solder pad.

2. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.

3. Device mounted on 50mm x 50mm x 1.6mm Cu Plate Heatsink.

